

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

Claim 1 (currently amended): A probe pin array, comprising:
a housing having a first surface and a second surface; and
a plurality of probe pins extending between said housing first surface and said housing said second surface, wherein said plurality of probe pins extend substantially perpendicularly from said housing second surface and wherein said plurality of probe pins each further include a leading end having a taper between about 10 and 25 degrees, and wherein said plurality of probe pins each has a diameter of between about 30% and 60% of a diameter of a pin of a pin grid array microelectronic device to be inserted into a socket to be tested by said plurality of probe pins.

Claim 2 (original): The probe pin array of claim 1, wherein said leading end taper is about 15 degrees.

Claim 3 (original): The probe pin array of claim 1, wherein said plurality of probe pins each comprise steel coated with gold.

Claim 4 (canceled): The probe pin array of claim 3, wherein said plurality of probe pins each has a diameter of between about 30% and 60% of a diameter of a pin of a pin grid array microelectronic device to be inserted into a socket to be tested by said plurality of probe pins.

Claim 5 (currently amended): ~~The probe pin array of claim 1,~~ A probe pin array,
comprising:

a housing having a first surface and a second surface; and

a plurality of probe pins extending between said housing first surface and said housing
said second surface, wherein said plurality of probe pins extend substantially perpendicularly
from said housing second surface and wherein said plurality of probe pins each further include a
leading end having a taper between about 10 and 25 degrees, and

~~further including~~ an alignment guide extending from said housing second surface having
a chamfered surface with an angle of between about 45 and 70 degrees from planar with said
housing second surface.

Claim 6 (original): The probe pin array of claim 5, wherein said chamfered surface has
an angle of about 60 degrees from planar with said housing second surface.

Claim 7 (currently amended): A probe pin array, comprising:

a housing having a first and a second surface;

a plurality of non-spring loaded probe pins extending between said housing first surface
and said housing second surface, wherein said plurality of non-spring loaded probe pins extend
substantially perpendicularly from said housing second surface, wherein said plurality of probe
pins each has a diameter of between about 30% and 60% of a diameter of a pin of a pin grid array
microelectronic device to be inserted into a socket to be tested by said plurality of probe pins;

and

at least one alignment guide extending from said housing second surface having at least one chamfered surface oriented toward said plurality of non-spring loaded probe pins.

Claim 8 (original): The probe pin array of claim 7, wherein said plurality of probe pins each further include a leading end having a taper between about 10 and 25 degrees.

Claim 9 (original): The probe pin array of claim 8, wherein said leading end taper is about 15 degrees.

Claim 10 (original): The probe pin array of claim 7, wherein said plurality of probe pins each comprise steel coated with gold.

Claim 11 (canceled): The probe pin array of claim 10, wherein said plurality of probe pins each has a diameter of between about 30% and 60% of a diameter of a pin of a pin grid array microelectronic device to be inserted into a socket to be tested by said plurality of probe pins.

Claim 12 (currently amended): ~~The probe pin array of claim 7,~~ A probe pin array,
comprising:

a housing having a first and a second surface;

a plurality of non-spring loaded probe pins extending between said housing first surface and said housing second surface, wherein said plurality of non-spring loaded probe pins extend

substantially perpendicularly from said housing second surface; and

at least one alignment guide extending from said housing second surface having at least one chamfered surface oriented toward said plurality of non-spring loaded probe pins, wherein said alignment guide chamfered surface has an angle of between about 45 and 70 degrees from planar with said housing second surface.

Claim 13 (original): The probe pin array of claim 12, wherein said chamfered surface has an angle of about 60 degrees from planar with said housing second surface.

Claim 14 (currently amended): A probe pin array, comprising:

a housing having a first and a second surface;

a carrier having a first surface and a second surface, wherein said carrier second surface abuts said housing first surface;

a plurality of non-spring loaded probe pins extending between said housing first surface and said housing second surface and extending between said housing first surface and said housing second surface, wherein said plurality of non-spring loaded probe pins extend substantially perpendicularly from said housing second surface, and wherein said plurality of probe pins each has a diameter of between about 30% and 60% of a diameter of a pin of a pin grid array microelectronic device to be inserted into a socket to be tested by said plurality of probe pins; and

at least one alignment guide extending from said housing second surface having at least one chamfered surface oriented toward said plurality of non-spring loaded probe pins.

Claim 15 (original): The probe pin array of claim 14, wherein said plurality of probe pins each further include a leading end having a taper between about 10 and 25 degrees.

Claim 16 (original): The probe pin array of claim 15, wherein said leading end taper is about 15 degrees.

Claim 17 (original): The probe pin array of claim 14, wherein said plurality of probe pins each comprise steel coated with gold.

Claim 18 (canceled): The probe pin array of claim 17, wherein said plurality of probe pins each has a diameter of between about 30% and 60% of a diameter of a pin of a pin grid array microelectronic device to be inserted into a socket to be tested by said plurality of probe pins.

Claim 19 (currently amended): ~~The probe pin array of claim 14,~~ A probe pin array,
comprising:

a housing having a first and a second surface;

a carrier having a first surface and a second surface, wherein said carrier second surface
abuts said housing first surface;

a plurality of non-spring loaded probe pins extending between said housing first surface
and said housing second surface and extending between said housing first surface and said
housing second surface, wherein said plurality of non-spring loaded probe pins extend

substantially perpendicularly from said housing second surface; and

at least one alignment guide extending from said housing second surface having at least one chamfered surface oriented toward said plurality of non-spring loaded probe pins, and
wherein said alignment guide chamfered surface has an angle of between about 45 and 70 degrees from planar with said housing second surface.

Claim 20 (previously presented): The probe pin array of claim 19, wherein said chamfered surface has an angle of about 60 degrees from planar with said housing second surface.